

## STATEMENT OF WORK FORMAT

PR: \_\_\_\_\_

**Note: Only use the sections that are applicable to your service procurement.**

### Background

- Wire bonding is used to create the electrical interconnects from our devices to our read outs.
- Wire bonding enables us to precisely attach wires to the input and output pads of our devices.
- Wire bonding is the industry standard for electrical interconnects on devices.

### Scope

- This tool will be used for gold ball bonding as well as gold and aluminum wedge bonding.

### Requirements

- The tool shall be equipped with the capabilities of both ball and wedge bonding.
- The tool shall come with a Nikon SMZ660 microscope kit
- The tool shall include spool holders for ½” and 2” spools.
- The tool shall include a 2” ribbon holder.
- The tool shall come with a built in stage temperature control.
- The tool shall have a motorized y-axis with programmable step back for both Ball Bonding and Wedge Bonding.
- The tool shall have manual and semi-automatic z control. With the manual lever on the left side of the tool.

### Deliverables or Delivery Schedule

- One model 4700 convertible wire bonder
- One Nikon SMZ660 microscope kit with Nikon 20X eyepieces.
- The tool shall include a manual.

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Signature

1/18/2012  
Date